SD650-N V3 overview

Product features, technical specifications

ThinkSystem SD650-N V3 product overview

The ThinkSystem SD650-N V3 server is a fifth-generation Neptune DWC platform. An SD650-N V3 tray combines one CPU compute node and one NVIDIA H100 GPU node mounted on a shared 1U tray with a water loop covering all the major heat sources in the nodes. The same GPU node is used in both the SD650-N V3 and SD665-N V3.





Features and specifications

Features	Descriptions
Form factor	1U DWC tray with two nodes
Node type	One CPU compute node (right node) and one GPU node (left node)
CPU	Two 4 th Gen Intel Xeon Scalable processors
GPU	Four NVIDIA H100 SXM5 GPUs
Storage	 Up to two 2.5-inch 7 mm SATA/NVMe drives in the CPU node only Up to one 2.5-inch 15 mm SATA/NVMe drive in the CPU node only Up to one M.2 adapter in the CPU node only
DIMM	Sixteen DIMM slots in the CPU node • 32 or 64 GB ECC RDIMMs or 128 GB 3DS RDIMMs • Up to 1 TB of memory with 64 GB RDIMMs in the CPU node • Up to 2 TB of memory with 128 GB 3DS RDIMMs in the CPU node
Networking	 A single 1 Gb Ethernet port with RJ45 connector – shared between the operating system and XCC Two 25 Gb SFP28 ports. One port is shared between the operating system and XCC

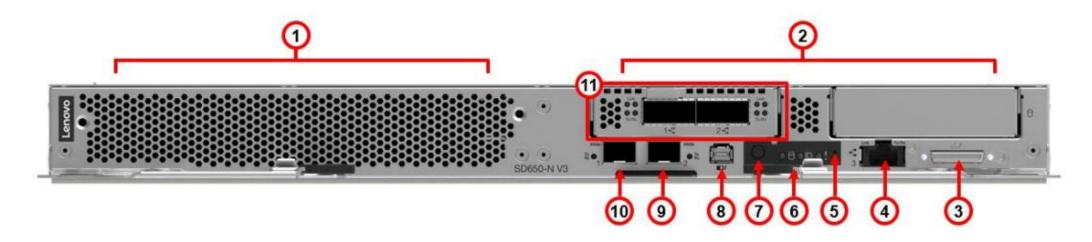
Note: For the latest specifications, refer to the SD650-N V3 product guide on Lenovo Press: https://lenovopress.lenovo.com/

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Networking	A single 1 Gb Ethernet port with RJ45 connector – shared between the operating system and XCC Two 25 Gb SFP28 ports. One port is shared between the operating system and XCC
PCle slots	Two PCle 5.0 x16 slots with a low-profile form factor on the front of the CPU node
Management interface	XCC2 embedded Support for LXCE Support for LXCA Optional external diagnostics handset with an LCD display

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ThinkSystem SD650-N V3 front view

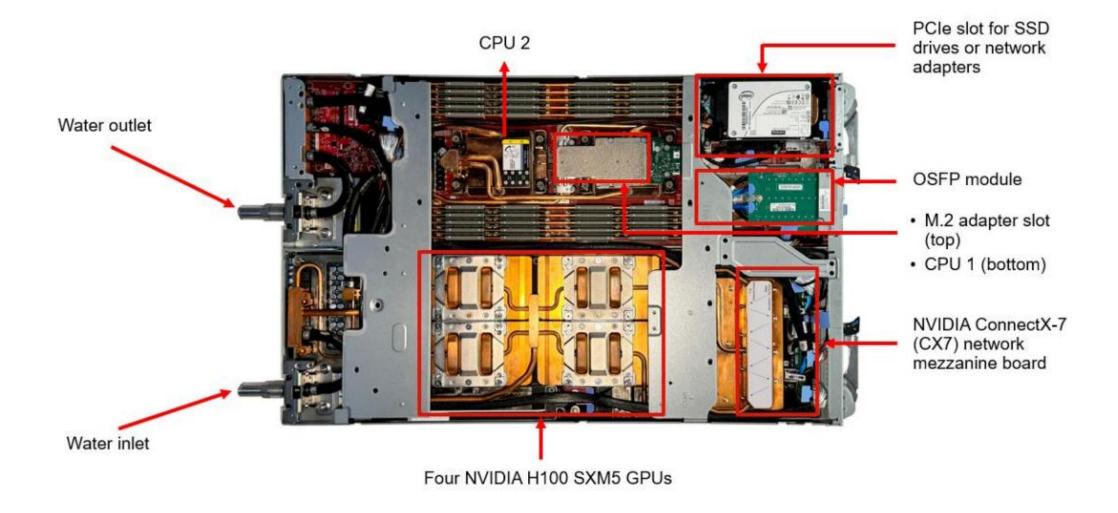


- Left GPU node
- Right CPU node
- (3) USB 3.0 console breakout cable connector
- 1 Gb RJ45 Ethernet port with share-NIC feature for XCC
- 5 NMI button
- 6 Front operator panel LEDs

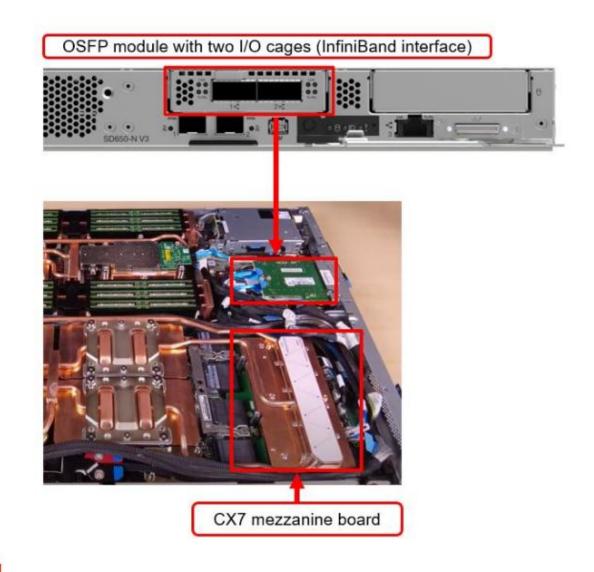
- Node power button with LED
- 8 External diagnostic handset connector
- 9 25 Gb SFP28 Ethernet port
- 25 Gb SFP28 Ethernet port with share-NIC feature for XCC
- OSFP module



ThinkSystem SD650-N V3 inside view



OSFP module



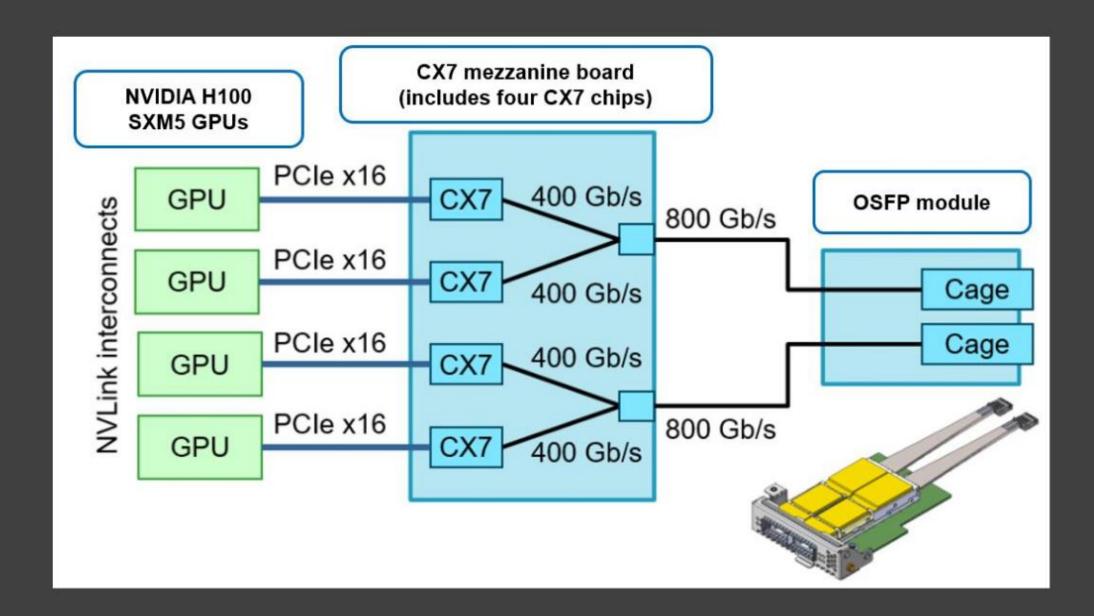
The SD650-N V3 supports an OSFP module in the CPU node for high speed I/O.

The OSFP module connects to the CX7 mezzanine board in the GPU node, and it contains two InfiniBand interface cages. Each cage supports up to an 800 Gb transceiver.

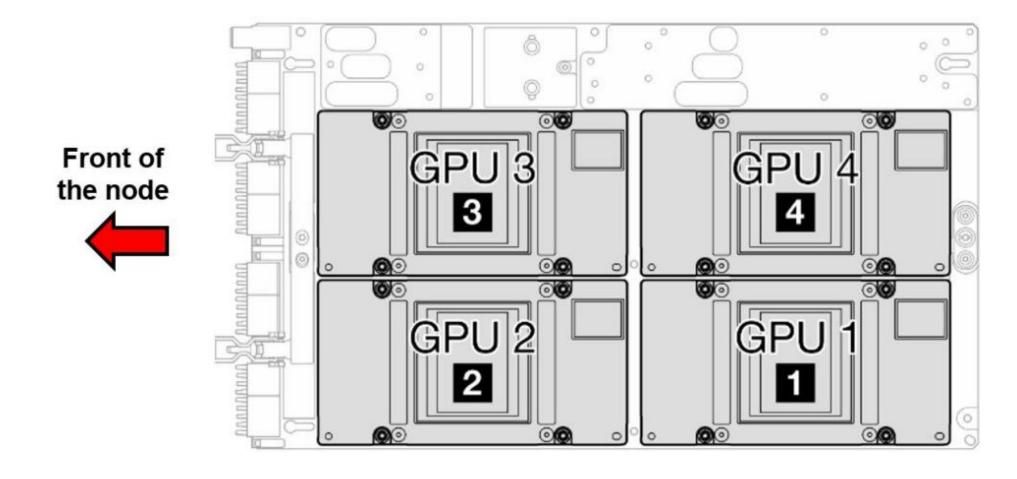
Click <u>HERE</u> to see the OSFP module and CX7 mezzanine board connection diagram.





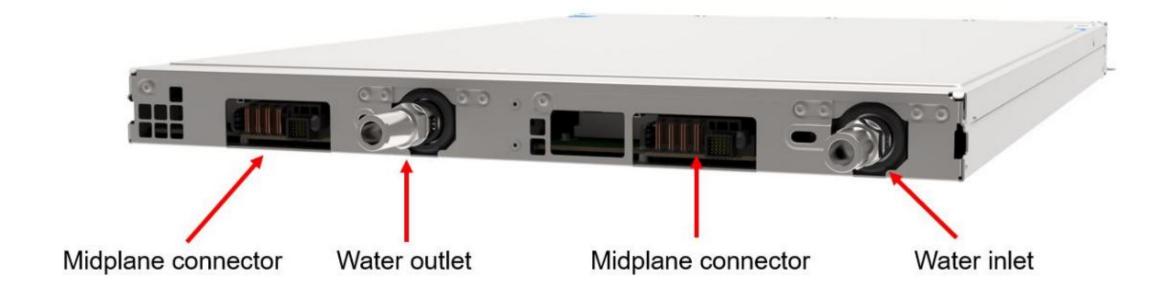


SD650-N V3 GPU numbering





ThinkSystem SD650-N V3 rear view



Note: The SD650-N V3, SD650 V3, and SD650-I V3 have the same rear view.



ThinkSystem SD650-N V3 front configurations



Two PCIe adapters in the CPU node configuration

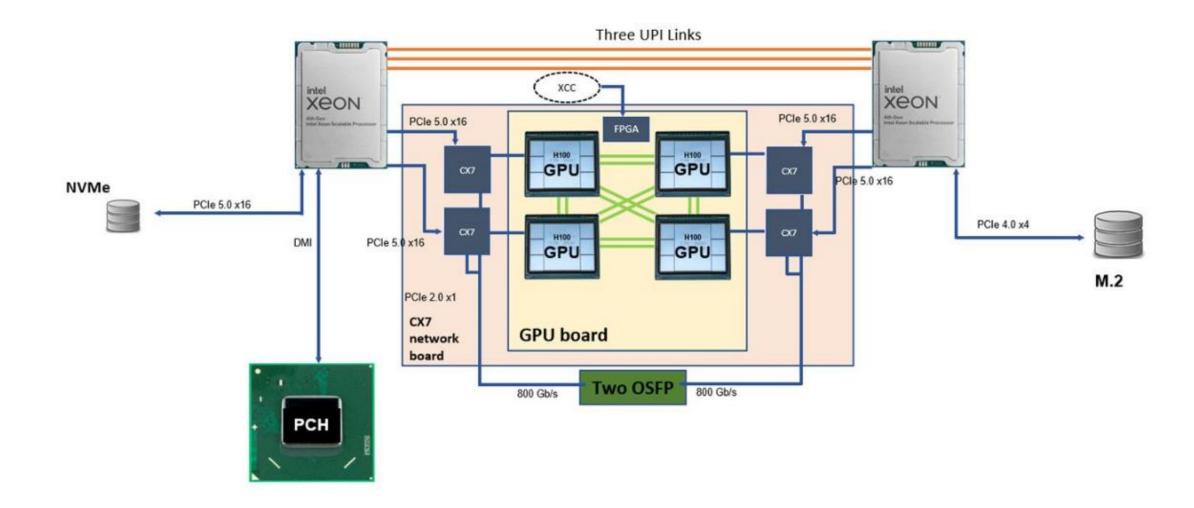


One PCle adapter and one drive tray in the CPU node configuration

Note: The SD650-N V3 SSD drives are not hot-swappable. Before replacing a drive, power off the node, remove the trays from the enclosure, and remove the top cover.



ThinkSystem SD650-N V3 block diagram





ThinkSystem SD650-N V3 breakout cable

As with the SD650 V3, the SD650-N V3 supports a local console through a KVM breakout cable. The cable connects to the port on the front of the CPU node.

